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TITLE: COPPER FOIL FOR PRINTED WIRING BOARD

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INVENTOR-INFORMATION:

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ABSTRACT:

PURPOSE: To have adhesion equal to the case where a conventional chromium layer is used as a middle layer by etching a copper layer and an Ni-Cr copper layer successively in one kind of etchant, using the Ni-Cr copper layer, where nickel is added to chromium, as the middle layer between a supporting substrate and the copper layer.

CONSTITUTION: In a copper foil for a printed wiring board, an Ni-Cr copper layer, where Ni is 5-89 atomic %, is provided as a middle layer, between the supporting substrate 1 and the copper layers 3 and 4. In the constitution of the copper foil, the Ni-Cr-OX oxide made at the interface between the Ni-Cr copper layer 2 and the supporting substrate 1 is fine and high in adhesion similar to chromium oxide. Hereby, the interface between the Ni-Cr copper layer 2 and the copper layers 3 and 4 made thereon becomes strong coupling between metal and metal. Therefore, for the copper layers 3 and 4 under which the Ni-Cr copper layer 2 is made as the middle layer, the adhesive strength with the supporting substrate 1 becomes a high value of 1000g/cm.